Materials Declaration

Package	SC70
Body Size	--
LeadCount	5
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
OCN	16	3.63 E-04	62874
SiO2	80	1.82 E-03	314368
Sb2O3	2.4	5.45 E-05	9431
Br	0.6	1.36 E-05	2358
Carbon Black	1	2.27 E-05	3930

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Fe	58.4	1.50 E-03	258807
Ni	41	1.05 E-03	181696
Mn	0.4	1.02 E-05	1773
Si	0.2	5.12 E-06	886

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.00 E-04	17311

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	5.83 E-04	100981

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.33 E-05	5770

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.10 E-04	36353

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.00 E-06	866
Ag Filler	75	1.50 E-05	2597

Package Totals

Weight (g)	PPM
5.78 E-03	1000000

Molding Compound

Item	PPM	Method
Pb	<10.38	ICP AES
Cd	0.0039	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

CRS-KS-E

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ADI Proprietary

07/21/04

Materials Declaration

Package	SC70 - COL
Body Size	--
LeadCount	5
Option	NiPdAu

Molding Compound

Substance	% of Compound	Weight (g)	PPM
Silica	87.3	2.88 E-03	470742
Phenol Resin	4.5	1.49 E-04	24265
Epoxy Resin 1	3.0	9.90 E-05	16177
Epoxy Resin 2	3.0	9.90 E-05	16177
Others	2.0	6.60 E-05	10784
Carbon Black	0.2	6.60 E-06	1078
Subtotal	100	3.30 E-03	539223

Leadframe

Substance	% of Leadframe	Weight (g)	PPM
Copper	97.5	2.46 E-03	402676
Iron	2.35	5.94 E-05	9706
Zinc	0.12	3.03 E-06	496
Phosphorus	0.03	7.58 E-07	124
Subtotal	100	2.53 E-03	413001

Internal Leadframe Plating/External Leadframe Plating

Substance	% of Plating	Weight (g)	PPM
Nickel	90.91	2.94 E-05	4811
Palladium	7.91	2.56 E-06	418
Gold	1.19	3.84 E-07	63
Subtotal	100.00	3.24 E-05	5292

Bond Wires

Substance	% of Wire	Weight (g)	PPM
Gold	99.99	3.00 E-05	4902

Chip

Substance	% of Chip	Weight (g)	PPM
Doped Silicon	100	2.10 E-04	34314

Die Attach

Substance	% of Die Attach	Weight (g)	PPM
Epoxy Resin	31	6.20 E-06	1013
Metal Oxide	31	6.20 E-06	1013
Glycol ethers	22	4.40 E-06	719
Silica	8	1.60 E-06	261
Curing agent & hardener	8	1.60 E-06	261
Subtotal	100	2.00 E-05	3268

Molding Compound

Substance	PPM	Method
Lead	Not Detected	USEPA 3050B. ICP-OES.
Cadmium	Not Detected	EN1122, method B:2001. ICP-OES.
Mercury	Not Detected	USEPA 3052. ICP-OES.
Chromium+6	Not Detected	EPA 3060A/7196A. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	EPA 3540C/3550B. GC-MS.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	EPA 3540C/3550B. GC-MS.

Die Attach

Substance	PPM	Method
Lead	Not Detected	Draft IEC 62321. ICP-OES.
Cadmium	Not Detected	Draft IEC 62321. ICP-OES.
Mercury	Not Detected	Draft IEC 62321. ICP-OES.
Chromium+6	Not Detected	Draft IEC 62321. UV-VIS.
Polybrominated biphenyls (PBB)	Not Detected	Draft IEC 62321. GC-MSD.
Polybrominated Diphenyl Ethers (PBDE)	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
6.12 E-03	1000000

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Materials Declaration

Package	SC70 -
Body Size	--
LeadCount	5
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
OCN	16	3.63 E-04	62874
SiO2	80	1.82 E-03	314368
Sb2O3	2.4	5.45 E-05	9431
Br	0.6	1.36 E-05	2358
Carbon Black	1	2.27 E-05	3930

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Fe	58.4	1.50 E-03	258807
Ni	41	1.05 E-03	181696
Mn	0.4	1.02 E-05	1773
Si	0.2	5.12 E-06	886

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	1.00 E-04	17311

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	4.96 E-04	85834
Pb	15	8.75 E-05	15147

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.33 E-05	5770

Chip

	% of Chip	Weight (g)	PPM
Si	100	2.10 E-04	36353

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.00 E-06	866
Ag Filler	75	1.50 E-05	2597

Package Totals

Weight (g)	PPM
5.78 E-03	1000000

Molding Compound

Item	PPM	Method
Pb	<10.38	ICP AES
Cd	0.0039	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

CRS-KS-A

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